My TinySine

Bluetooth Module Datasheet

Model: TS3031

Version: V1.2

2021-11-21

Tinysine Electronics.

Tel: +86-551-65365921 Ext 801

E-mail: <u>customerservice@tinyosshop.com</u>

Web: www.tinyosshop.com

Hefei, Anhui, China

List of Contents

1 Introduction	3
2 Key Features	3
3 Applications	4
4 Block Diagram	4
5 General specifications	4
6 Module Package Information	5
6.1 Pinout Diagram and package dimensions	5
6.2 Module Pin descriptions	6
7 Electrical Characteristics	10
7.1 Absolute Maximum Ratings	10
7.2 Recommended Operating Conditions	10
8 Recommended reflow temperature profile	11

1 Introduction

Tinysine Electronics introduces the pioneer of the Bluetooth 5.1 modules TS3031 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC3031 BGA chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.1 system.

2 Key Features

TS3031(QCC3031) Features

- Qualified to Bluetooth® v5.1 specification
- 120 MHz Qualcomm® Kalimba™ audio DSPs
- 32 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- Advanced audio algorithms
- High-performance 24-bit stereo audio interface
- Digital and analog microphone interfaces
- aptX, aptX HD, aptX Low Latency, SBC, and AAC audio codecs support
- Serial interfaces: UART, Bit Serializer (I² C/SPI),USB 2.0
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

Application subsystem

- Dual core application subsystem 32 MHz operation
- 32-bit Firmware Processor:
 - Reserved for system use
 - Runs Bluetooth upper stack, profiles, house-keeping code
- 32-bit Developer Processor:Runs developer applications
- Both cores execute code from external flash memory using QSPI clocked at 32 MHz
- On-chip caches per core allow for optimized performance and power consumption

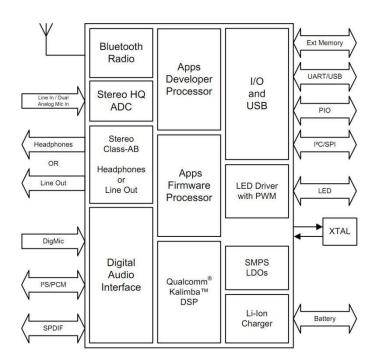
Bluetooth subsystem

- Qualified to Bluetooth v5.1 specification including 2 Mbps Bluetooth low energy (Production parts)
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth low energy, and mixed topologies supported
- Class 1 support

3 Applications

Wired/wireless speakers

4 Block Diagram

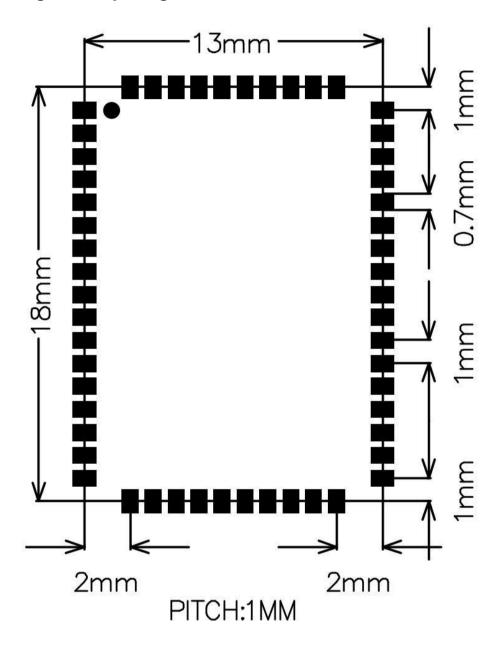


5 General specifications

Model Name	TS3031
Product Description	Bluetooth 5.1 Class1.5 Module
Bluetooth Standard	Bluetooth 5.1
Chipset	QCC3031 QFN
Dimension	18mm x 13mm x 2.5mm
Operating Conditions	
Voltage	2.8~4.3V
Temperature	-40∼+85℃
Storage Temperature	-40∼+85℃
Electrical Specifications	
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
π /4 DQPSK Receive Sensitivity	-92dBm
8DPSK Receive Sensitivity	-85dBm

6 Module Package Information

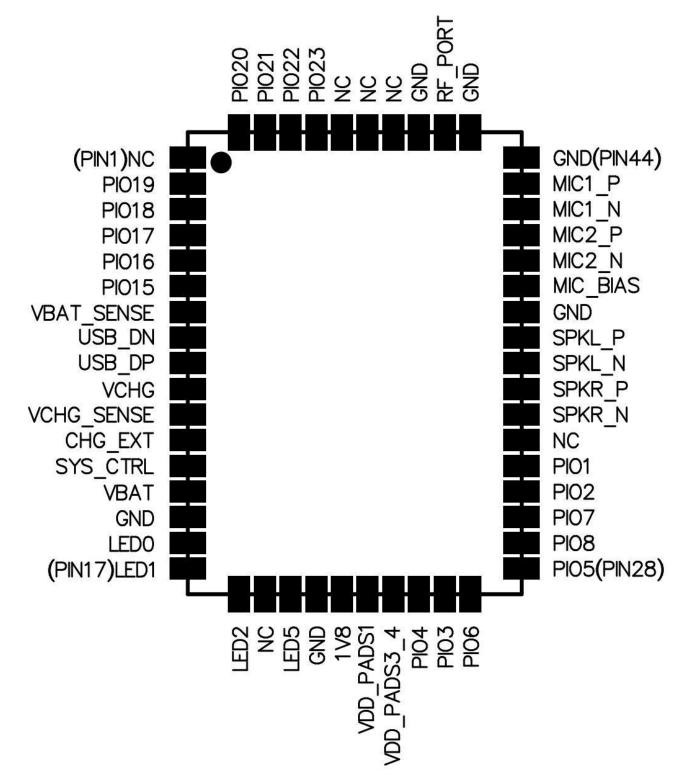
6.1 Pinout Diagram and package dimensions



Unit: MM

Recommended PCB layout footprint

6.2 Module Pin descriptions



Pin#	Pin Name	Pin type	Description
1	NC	NC	NC
		Digital: Bidirectional with	Programmable I/O line 19.
2	PIO[19]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DIN[0]
3	PIO[18]	Digital: Bidirectional with	Programmable I/O line 18.

	1	programmable strongth internal	Alternative function:
		programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[0]
	DIOM TI	Digital: Bidirectional with	Programmable I/O line 17.
4	PIO[17]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_SYNC
		Digital: Bidirectional with	Programmable I/O line 16.
5	PIO[16]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_CLK
		Digital: Bidirectional with	Programmable I/O line 15.
6	PIO[15]	programmable strength internal	Alternative function:
		pull- up/pull-down	MCLK_OUT
7	VBAT_SENSE	Analog	Battery voltage sense input.
8	USB_DN	Digital	USB Full Speed device D- I/O. IEC-61000-4-2
	005_511	J.g.ta.	(device level) ESD Protection
9	USB_DP	Digital	USB Full Speed device D+ I/O. IEC-61000-4-2
9	035_51	Digital	(device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
			Charger input sense pin after external mode
			sense-resistor. High impedance.
11	VCHG_SENSE	Analog	
			NOTE If using internal charger or no charger,
			connect VCHG_SENSE direct to VCHG.
			External charger transistor current control. Connect
12	CHG_EXT	Analog	to base of external charger transistor as per
			application schematic.
			Typically connected to an ON/OFF push button.
			Boots device in response to a button press when
			power is still present from battery and/or charger but
13	SYS_CTRL	Digital input	software has placed the device in the OFF or
13		Digital Input	DORMANT state. Additionally useable as a digital
			input in normal operation. No pull.
			Additional function:
			PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
16	AIOI01/I EDIOI	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
10	AIO[0]/LED[0]	output.	LED output.
17	AIO[1]/ ED[1]	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
17	AIO[1]/LED[1]	output.	LED output.
18	AIO[2]/LED[2]	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
		output.	LED output.
19	NC	NC	NC
20	AIO(51/LED(5)	Analog or digital input/ open drain	General-purpose analog/digital input or open drain
	AIO[5]/LED[5]	output.	LED output.
21	GND	Ground	Ground
		1	

22	1V8	Supply	1.8V voltage output.	
23	VDD_PADS1	Supply	1.8 V/3.3 V PIO supply.	
24	VDD_PADS3_4	Supply	1.8 V/3.3 V PIO supply.	
		Digital: Bidirectional with	Programmable I/O line 4.	
25	PIO[4]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MOSI[1]	
		Digital: Bidirectional with	Programmable I/O line 3.	
26	PIO[3]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MISO[2]	
		Digital: Bidirectional with	Programmable I/O line 6.	
27	PIO[6]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MOSI[0]	
		Digital: Bidirectional with	Programmable I/O line 5.	
28	PIO[5]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MISO[1]	
		Digital: Bidirectional with	Programmable I/O line 8.	
29	PIO[8]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_CLK	
		Digital: Bidirectional with	Programmable I/O line 7.	
30	PIO[7]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MISO[0]	
		Digital: Bidirectional with	Programmable I/O line 2.	
31	PIO[2]	programmable strength internal	Alternative function:	
		pull- up/pull-down	TBR_MISO[3]	
			Automatically defaults to RESET# mode when the	
		Digital: Bidirectional with	device is unpowered, or in off modes.	
32	PIO[1]	programmable strength internal	Reconfigurable as a PIO after boot.	
		pull- up/pull-down	Alternative function:	
			Programmable I/O line 1	
33	NC	NC	NC	
			Headphone/speaker differential right output,	
	ALIBIO LIBB ALCORUB AL		negative.	
34	AUDIO_HPR_N/ SPKR_N	Analog	Alternative function:	
			Differential right line output, negative	
			Headphone/speaker differential right output,	
0.5	ALIDIO LIDD DI ODICO D		positive.	
35	AUDIO_HPR_P/ SPKR_P	Analog	Alternative function:	
			Differential right line output, positive	
			Headphone/speaker differential left output,	
26	ALIDIO HDI NI/EDIZI N	Angles	negative.	
36	AUDIO_HPL_N/ SPKL_N	Analog	Alternative function:	
			Differential left line output, negative	
			Headphone/speaker differential left output, positive.	
37	AUDIO_HPL_P/ SPKL_P	Analog	Alternative function:	
		The state of the s	I I	

38	GND	Ground	Ground
39	AUDIO_MIC_BIAS	Analog	Mic bias output.
			Microphone differential 2 input, negative.
40	AUDIO_MIC2_N/ LINEIN_R_N	Analog	Alternative function:
			Differential audio line input right, negative
			Microphone differential 2 input, positive.
41	AUDIO_MIC2_P/ LINEIN_R_P	Analog	Alternative function:
			Differential audio line input right, positive
			Microphone differential 1 input, negative.
42	AUDIO_MIC1_N/ LINEIN_L_N	Analog	Alternative function:
			Differential audio line input left, negative
			Microphone differential 1 input, positive.
43	AUDIO_MIC1_P/ LINEIN_L_P	Analog	Alternative function:
			Differential audio line input left, positive
44	GND	Ground	Ground
45	GND	Ground	Ground
46	BT_RF	RF	Bluetooth transmit/receive.
47	GND	Ground	Ground
48	NC	NC	NC
49	NC	NC	NC
50	NC	NC	NC
		Digital: Bidirectional with	
51	PIO[23]	programmable strength internal	Programmable I/O line 23.
		pull- up/pull-down	
		Digital: Bidirectional with	
52	PIO[22]	programmable strength internal	Programmable I/O line 22.
		pull- up/pull-down	
		Digital: Bidirectional with	Programmable I/O line 21.
53	PIO[21]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[2]
		Digital: Bidirectional with	Programmable I/O line 20.
54	PIO[20]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[1]

7 Electrical Characteristics

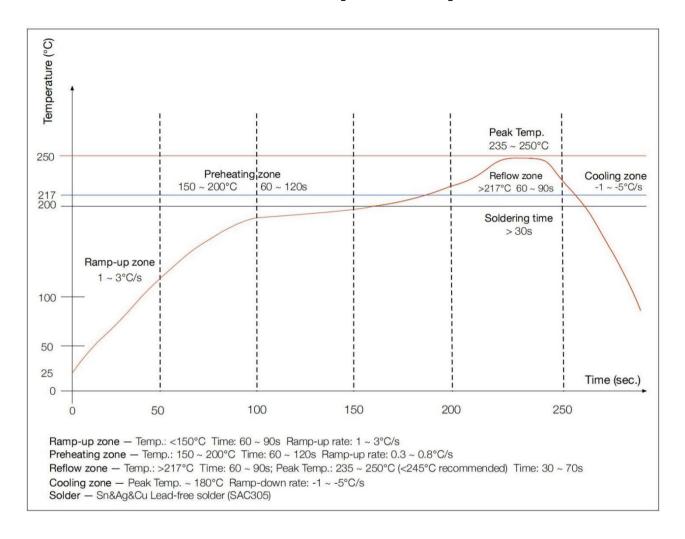
7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	-40℃	+85℃

7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40℃	+85℃
Supply voltage: VBAT	+2.8V	+4.3V

8 Recommended reflow temperature profile



The module Must go through 125°C baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线,我们建议让模块下次上线前务必以 125℃烘烤 9 小时以上!

Record of Changes

Data	Revision	Description
2019-11-25	V1.0	Original publication of this document.
2020-04-23	V1.1	Fix PIN definition.
2021-11-21	V1.2	Updata bluetooth 5.1 version and temperature.

IMPORTANT NOTICE

Tinysine Technologies Co.,Ltd reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current. All products are sold subject to the Tinysine terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

Tinysine warrants performance of its products to specifications applicable at the time of sale in accordance with Tinysine's standard warranty. Testing and other quality control techniques are utilized to the extent Tinysine deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

In order to minimize risks associated with customer applications, adequate design and operating safeguards must be used by the customer to minimize inherent or procedural hazards. Tinysine products are not authorized for use as critical components in life support devices or systems without the express written approval of an officer of the company. Life support devices or systems are devices or systems that are intended for surgical implant into the body, or support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided, can be reasonably expected to result in a significant injury to the user. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Tinysine assumes no liability for applications assistance or customer product design. Tinysine does not warrant or represent that any license, either express or implied, is granted under any patent right, mask work right, or other intellectual property right of Tinysine covering or relating or any combination, machine, or process in which such products or services might be or are used.

Tel: +86-551-65369521 Ext 801

Fax: +86-551-65365931
Web: www.tinyosshop.com

E-mail: customerservice@tinyosshop.com